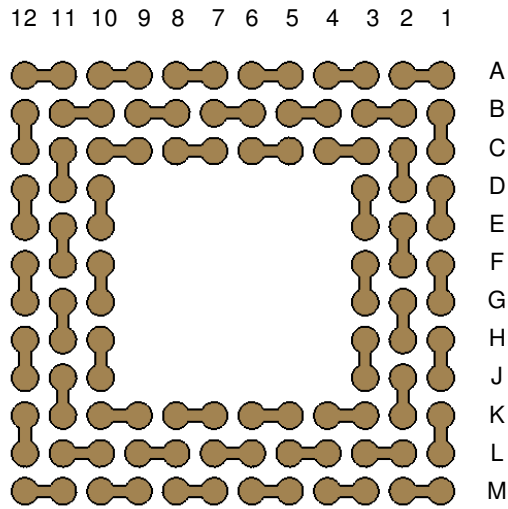


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.30mm [11.8 MIL].
  - 5) PAD Cu DIAMETER: 0.356mm [14 MIL].
  - 6) SUBSTRATE MATERIAL: BT.
  - 7) DUMMY DIE IS OPTIONAL.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

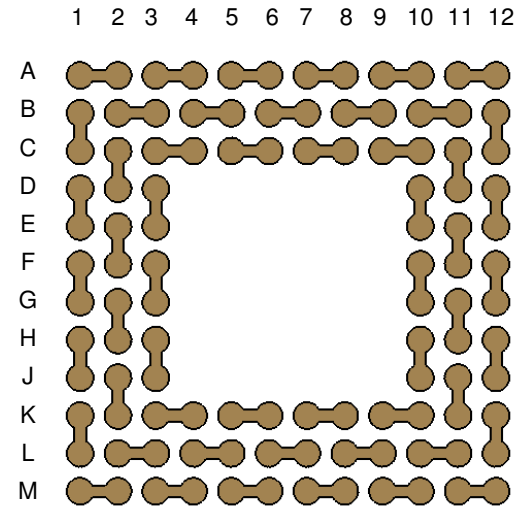
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
CSP108T.5C-DC124D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
CSP108T.5-DC124D	Sn63/Pb37	NO	NO	YES
LGA108T.5G-DC124D	Ni Au PAD	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE	<b>TopLine</b> CSP108T.5C-DC124D DAISY CHAIN DUMMY				
X.XX	+/- 0.01	DRAWN J. Hines		6/9/2012					
X.XXX	+/- 0.005	ENG			SCALE		SIZE	DRAWING NO.	REV
X.XXXX	+/- 0.0005	MFG			10:1	A	551240	A	
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION			DO NOT SCALE DRAWING		SHEET 1 OF 2		
ALL DIMENSIONS IN		<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS							

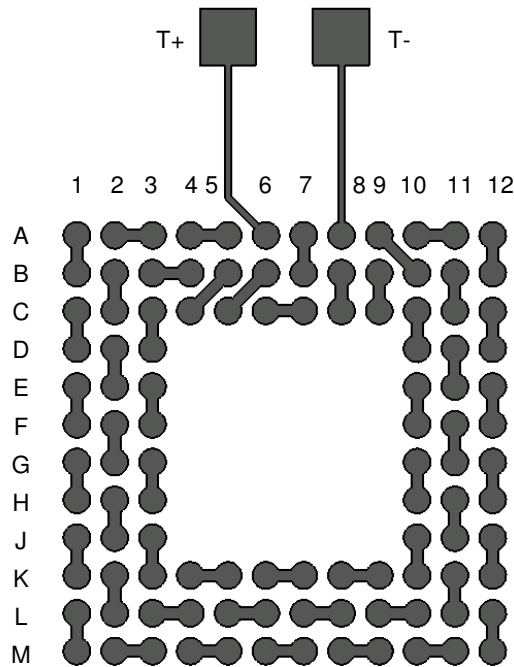
BALL VIEW



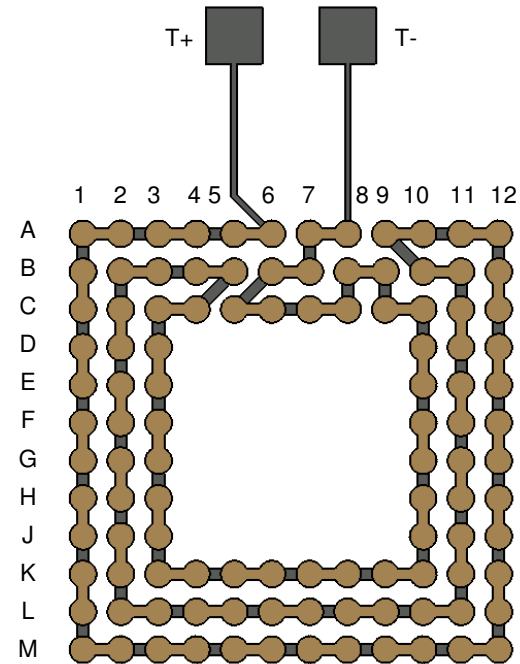
BOTTOM SIDE  
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.356mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.154mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.30mm (11.8 MIL).

**TopLine**®

TITLE			
CSP108T.5C-DC124D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	551240	A
DO NOT SCALE DRAWING			SHEET 2 OF 2